

Product Change Notification - KSRA-19GIRS482

Date: 25 Feb 2018
Product Category: 8-bit PIC Microcontrollers; 16-Bit - Microcontrollers and Digital Signal Controllers
Notification subject: CCB 2923 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products for 200K wafer technology available in 28L QFN package at NSEB assembly site
Notification text: **PCN Status:**
 Final notification

PCN Type:
 Manufacturing Change

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products for 200K wafer technology available in 28L QFN package at NSEB assembly site

Pre Change:

Using gold (Au) bond wire, 8200T and 8600 die attach and G770HCD and G700LTD mold compound material.

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach and G700LTD mold compound material.

Pre and Post Change Summary:

	Pre Change		Post Change
Assembly Site	UTAC Thai Limited LTD. (NSEB)		UTAC Thai Limited LTD. (NSEB)
Wire material	Au Wire		CuPdAu Wire
Die attach material	8200T	8600	8600
Molding compound material	G770HCD	G700LTD	G700LTD
Lead frame material	EFTEC-64T		EFTEC-64T

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying CuPdAu bond wire at NSEB assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

March 25, 2018 (date code: 1813)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts

Time Table Summary:

Workweek	April 2017					-->	February 2018					March 2018				
	13	14	15	16	17		05	06	07	08	09	10	11	12	13	
Initial PCN Issue Date					X											
Qual Report Availability										X						
Final PCN Issue Date										X						
Estimated Implementation Date															X	

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report

Revision History:

April 27, 2017: Issued initial notification.

February 25, 2018: Issued final notification. Attached the Qualification Report. Revised the affected parts list. Provided estimated first ship date on March 25, 2018.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

- [PCN_KSRA-19GIRS482_Affected CPN.pdf](#)
- [PCN_KSRA-19GIRS482_Qual Report.pdf](#)
- [PCN_KSRA-19GIRS482_Affected CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PCN_KSRA-19GIRS482
CATALOG_PART_NBR
HA2223-I/ML
HA2223T-I/ML
PIC16F1713-E/ML
PIC16F1713-I/ML
PIC16F1713T-I/ML
PIC16F1716-E/ML
PIC16F1716-I/ML
PIC16F1716T-I/ML
PIC16F1718-E/ML
PIC16F1718-I/ML
PIC16F1718T-I/ML
PIC16F1782-E/ML
PIC16F1782-I/ML
PIC16F1782T-E/ML
PIC16F1782T-I/ML
PIC16F1783-E/ML
PIC16F1783-I/ML
PIC16F1783T-E/ML
PIC16F1783T-I/ML
PIC16F1786-E/ML
PIC16F1786-I/ML
PIC16F1786T-I/ML
PIC16F1788-E/ML
PIC16F1788-I/ML
PIC16F1788T-E/ML
PIC16F1788T-I/ML
PIC16F1826-E/ML
PIC16F1826-I/ML
PIC16F1826T-I/ML
PIC16F1827-E/ML
PIC16F1827-I/ML
PIC16F1827T-I/ML
PIC16F1847-E/ML
PIC16F1847-I/ML
PIC16F1847T-I/ML
PIC16F1933-E/ML
PIC16F1933-I/ML
PIC16F1933T-E/ML
PIC16F1933T-I/ML
PIC16F1936-E/ML
PIC16F1936-I/ML
PIC16F1936T-I/ML
PIC16F1938-E/ML

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Affected Catalog Part Numbers (CPN)

PCN_KSRA-19GIRS482
CATALOG_PART_NBR
PIC16F1938-I/ML
PIC16F1938-I/MLRA2
PIC16F1938T-I/ML
PIC16F1938T-I/MLRA2
PIC16F722A-E/ML
PIC16F722A-I/ML
PIC16F722AT-I/ML
PIC16F722-E/ML
PIC16F722-I/ML
PIC16F722T-I/ML
PIC16F723A-E/ML
PIC16F723A-I/ML
PIC16F723AT-I/ML
PIC16F723-E/ML
PIC16F723-I/ML
PIC16F723T-E/ML
PIC16F723T-I/ML
PIC16F726-E/ML
PIC16F726-I/ML
PIC16F726T-I/ML
PIC16LF1713-E/ML
PIC16LF1713-I/ML
PIC16LF1713T-I/ML
PIC16LF1716-E/ML
PIC16LF1716-I/ML
PIC16LF1716T-I/ML
PIC16LF1718-E/ML
PIC16LF1718-I/ML
PIC16LF1718T-I/ML
PIC16LF1782-E/ML
PIC16LF1782-I/ML
PIC16LF1782T-I/ML
PIC16LF1783-E/ML
PIC16LF1783-I/ML
PIC16LF1783T-I/ML
PIC16LF1786-E/ML
PIC16LF1786-I/ML
PIC16LF1786T-I/ML
PIC16LF1788-E/ML
PIC16LF1788-I/ML
PIC16LF1788T-I/ML
PIC16LF1826-E/ML
PIC16LF1826-I/ML

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PCN_KSRA-19GIRS482
CATALOG_PART_NBR
PIC16LF1826-I/MLC01
PIC16LF1826T-I/ML
PIC16LF1826T-I/MLC01
PIC16LF1827-E/ML
PIC16LF1827-I/ML
PIC16LF1827T-I/ML
PIC16LF1847-E/ML
PIC16LF1847-I/ML
PIC16LF1847T-I/ML
PIC16LF1933-E/ML
PIC16LF1933-I/ML
PIC16LF1933T-I/ML
PIC16LF1936-E/ML
PIC16LF1936-I/ML
PIC16LF1936T-I/ML
PIC16LF1936T-I/ML020
PIC16LF1938-E/ML
PIC16LF1938-I/ML
PIC16LF1938-I/MLC01
PIC16LF1938T-E/ML
PIC16LF1938T-I/ML
PIC16LF1938T-I/MLC01
PIC16LF722A-E/ML
PIC16LF722A-I/ML
PIC16LF722AT-I/ML
PIC16LF722-E/ML
PIC16LF722-I/ML
PIC16LF722T-I/ML
PIC16LF723A-E/ML
PIC16LF723A-I/ML
PIC16LF723AT-I/ML
PIC16LF723-E/ML
PIC16LF723-I/ML
PIC16LF723T-I/ML
PIC16LF726-E/ML
PIC16LF726-I/ML
PIC16LF726T-I/ML
PIC18F23K20-E/ML
PIC18F23K20-I/ML
PIC18F23K20T-E/ML
PIC18F23K20T-I/ML
PIC18F23K22-E/ML
PIC18F23K22-I/ML

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PCN_KSRA-19GIRS482
CATALOG_PART_NBR
PIC18F23K22T-E/ML
PIC18F23K22T-I/ML
PIC18F24K20-E/ML
PIC18F24K20-I/ML
PIC18F24K20T-I/ML
PIC18F24K20T-I/ML028
PIC18F24K22-E/ML
PIC18F24K22-I/ML
PIC18F24K22T-E/ML
PIC18F24K22T-I/ML
PIC18F24K50-E/ML
PIC18F24K50-I/ML
PIC18F24K50T-I/ML
PIC18F25K20-E/ML
PIC18F25K20-I/ML
PIC18F25K20-I/MLC02
PIC18F25K20-I/MLC05
PIC18F25K20-I/MLC10
PIC18F25K20-I/MLLPR
PIC18F25K20T-E/ML
PIC18F25K20T-I/ML
PIC18F25K20T-I/MLC02
PIC18F25K20T-I/MLC10
PIC18F25K22-E/ML
PIC18F25K22-I/ML
PIC18F25K22T-E/ML
PIC18F25K22T-I/ML
PIC18F25K50-E/ML
PIC18F25K50-I/ML
PIC18F25K50T-E/ML
PIC18F25K50T-E/ML020
PIC18F25K50T-E/ML022
PIC18F25K50T-I/ML
PIC18F26K20-E/ML
PIC18F26K20-I/ML
PIC18F26K20-I/ML035
PIC18F26K20-I/ML045
PIC18F26K20-I/ML046
PIC18F26K20-I/ML047
PIC18F26K20-I/ML048
PIC18F26K20-I/ML049
PIC18F26K20-I/ML050
PIC18F26K20-I/MLC03

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PCN_KSRA-19GIRS482
CATALOG_PART_NBR
PIC18F26K20T-E/ML
PIC18F26K20T-I/ML
PIC18F26K20T-I/ML033
PIC18F26K20T-I/ML034
PIC18F26K20T-I/ML035
PIC18F26K20T-I/ML036
PIC18F26K20T-I/ML040
PIC18F26K20T-I/ML043
PIC18F26K20T-I/ML045
PIC18F26K20T-I/ML046
PIC18F26K20T-I/ML047
PIC18F26K20T-I/ML048
PIC18F26K20T-I/ML049
PIC18F26K20T-I/ML050
PIC18F26K20T-I/ML051
PIC18F26K20T-I/ML052
PIC18F26K20T-I/MLC03
PIC18F26K22-E/ML
PIC18F26K22-I/ML
PIC18F26K22T-E/ML
PIC18F26K22T-I/ML
PIC18F26K22T-I/ML024
PIC18LF23K22-E/ML
PIC18LF23K22-I/ML
PIC18LF23K22T-I/ML
PIC18LF23K22T-I/ML020
PIC18LF23K22T-I/ML021
PIC18LF24K22-E/ML
PIC18LF24K22-I/ML
PIC18LF24K22T-I/ML
PIC18LF24K50-E/ML
PIC18LF24K50-I/ML
PIC18LF24K50T-I/ML
PIC18LF25K22-E/ML
PIC18LF25K22-I/ML
PIC18LF25K22T-I/ML
PIC18LF25K50-E/ML
PIC18LF25K50-I/ML
PIC18LF25K50T-I/ML
PIC18LF26K22-E/ML
PIC18LF26K22-I/ML
PIC18LF26K22-I/MLC04
PIC18LF26K22-I/MLC05

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PCN_KSRA-19GIRS482
CATALOG_PART_NBR
PIC18LF26K22-I/MLC06
PIC18LF26K22T-E/ML
PIC18LF26K22T-I/ML
PIC18LF26K22T-I/ML024
PIC18LF26K22T-I/MLC02
PIC18LF26K22T-I/MLC04
PIC18LF26K22T-I/MLC05
PIC18LF26K22T-I/MLC06
PIC24F08KA102-E/ML
PIC24F08KA102-I/ML
PIC24F08KL302-E/ML
PIC24F08KL302-I/ML
PIC24F08KL302-I/MQ
PIC24F08KL302T-I/MQ
PIC24F08KL402-I/ML
PIC24F08KL402-I/MQ
PIC24F08KM202-I/ML
PIC24F16KA102-E/ML
PIC24F16KA102-I/ML
PIC24F16KA102T-I/ML
PIC24F16KA302-I/ML
PIC24F16KA302T-I/ML
PIC24F16KL402-E/MQ
PIC24F16KL402-I/ML
PIC24F16KL402-I/MQ
PIC24F16KL402T-I/ML
PIC24F16KL402T-I/MQ
PIC24F16KM102-I/ML
PIC24F16KM202-E/ML
PIC24F16KM202-I/ML
PIC24F32KA302-E/ML
PIC24F32KA302-I/ML
PIC24F32KA302T-E/ML
PIC24F32KA302T-I/ML
PIC24FV08KM202-I/ML
PIC24FV16KA302-I/ML
PIC24FV16KA302T-I/ML
PIC24FV16KM102-I/ML
PIC24FV16KM202-E/ML
PIC24FV16KM202-I/ML
PIC24FV16KM202T-I/ML
PIC24FV32KA302-I/ML
PIC24FV32KA302T-I/ML